Declaration of RoHS-compliant Products

Part Number: Applicable to AST-series, ASL-series
Product Name: GaAs Amplifier
Package Type: DFN6

Package Elements	Constituents	CAS No.	Weight (mg)	Weight %
Active Semiconductor Die	GaAs	1303-00-0	0.28	100
Leadframe	Cu	7440-50-8	4.261781	97.432
	Cr	7440-47-3	0.000437	0.01
	Fe	1309-37-1	0.102802	2.35
	P	7723-14-0	0.003609	0.0825
	Zn	7440-66-6	0.005468	0.125
Leadframe Plating	Sn	7440-31-5	0.249400	100
Epoxy Molding Compound	Silica Fused	60676-86-0	5.0802868	86.2
	Epoxy Resin A	129915-35-1	0.17678545	3
	Epoxy Resin B	129915-35-1	0.17678545	3
	Phenol Resin A	26834-02-6-	0.17678545	3
	Phenol Resin B	26834-02-6-	0.17678545	3
	Metal Hydroxide	-	0.0884041	1.5
	Carbon Black	1333-86-4	0.0176813	0.3
Epoxy Resin	Silver	7440-22-4	0.120783	74
	Epoxy Resin	129915-35-1	0.032644	20
	Gamma-Butyrolactone	96-48-0	0.004897	3
	Phenolic Resin	-	0.004897	3
Wire	Au	7440-57-5	2.850309	100
Total			**13.81**	

This information sheet is to declare all substances intentionally added in our DFN6 semiconductor products. Total weight of the package varies depending on active die size. The material data is evidenced by written declaration from our packaging company. The products listed above DO NOT CONTAIN intentionally added hazardous materials such as cadmium (Cd), mercury (Hg), hexavalent chromium (Cr^{6+}), polybrominated biphenyls (PBBs), polybrominated diphenylethers (PBDEs), bis(2-ethylhexyl) phthalate (DEHP), butyl benzyl phthalate (BBP), dibutyl phthalate (DBP), and diisobutyl phthalate (DIBP) except for 0.01 wt.% of lead (Pb), which COMPLY with the *RoHS3 Directive 2015/863/EU*. For further information, contact our Sales Department at sales@asb.co.kr.

Authorized Signature, ASB Inc.